

ABSTRACT

The invention relates to the manufacture of printed circuit boards having improved interlayer adhesion. More particularly, the present invention pertains to
5 adhesiveless printed circuit boards having excellent thermal performance and useful for producing high-density circuits. A metal foil coated with a polyimide film is laminated onto an etched surface of a polyimide substrate. Etching the substrate surface allows for strong adhesion of a pure polyimide film to the substrate.